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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	32
Number of Macrocells	512
Number of Gates	-
Number of I/O	208
Operating Temperature	0°C ~ 90°C (TJ)
Mounting Type	Surface Mount
Package / Case	256-LBGA
Supplier Device Package	256-FTBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc4512v-5ft256c

Product Term Allocator

The product term allocator assigns product terms from a cluster to either logic or control applications as required by the design being implemented. Product terms that are used as logic are steered into a 5-input OR gate associated with the cluster. Product terms that used for control are steered either to the macrocell or I/O cell associated with the cluster. Table 3 shows the available functions for each of the five product terms in the cluster. The OR gate output connects to the associated I/O cell, providing a fast path for narrow combinatorial functions, and to the logic allocator.

Table 3. Individual PT Steering

Product Term	Logic	Control
PT n	Logic PT	Single PT for XOR/OR
PT $n+1$	Logic PT	Individual Clock (PT Clock)
PT $n+2$	Logic PT	Individual Initialization or Individual Clock Enable (PT Initialization/CE)
PT $n+3$	Logic PT	Individual Initialization (PT Initialization)
PT $n+4$	Logic PT	Individual OE (PTOE)

Cluster Allocator

The cluster allocator allows clusters to be steered to neighboring macrocells, thus allowing the creation of functions with more product terms. Table 4 shows which clusters can be steered to which macrocells. Used in this manner, the cluster allocator can be used to form functions of up to 20 product terms. Additionally, the cluster allocator accepts inputs from the wide steering logic. Using these inputs, functions up to 80 product terms can be created.

Table 4. Available Clusters for Each Macrocell

Macrocell	Available Clusters			
M0	—	C0	C1	C2
M1	C0	C1	C2	C3
M2	C1	C2	C3	C4
M3	C2	C3	C4	C5
M4	C3	C4	C5	C6
M5	C4	C5	C6	C7
M6	C5	C6	C7	C8
M7	C6	C7	C8	C9
M8	C7	C8	C9	C10
M9	C8	C9	C10	C11
M10	C9	C10	C11	C12
M11	C10	C11	C12	C13
M12	C11	C12	C13	C14
M13	C12	C13	C14	C15
M14	C13	C14	C15	—
M15	C14	C15	—	—

Wide Steering Logic

The wide steering logic allows the output of the cluster allocator n to be connected to the input of the cluster allocator $n+4$. Thus, cluster chains can be formed with up to 80 product terms, supporting wide product term functions and allowing performance to be increased through a single GLB implementation. Table 5 shows the product term chains.

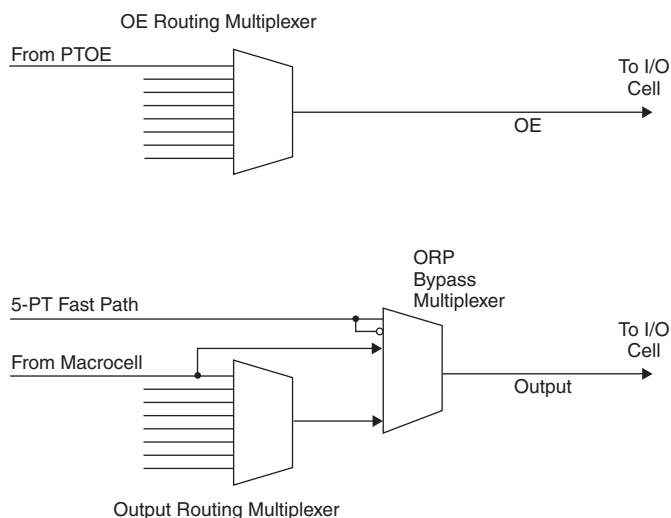
Output Routing Pool (ORP)

The Output Routing Pool allows macrocell outputs to be connected to any of several I/O cells within an I/O block. This provides greater flexibility in determining the pinout and allows design changes to occur without affecting the pinout. The output routing pool also provides a parallel capability for routing macrocell-level OE product terms. This allows the OE product term to follow the macrocell output as it is switched between I/O cells. Additionally, the output routing pool allows the macrocell output or true and complement forms of the 5-PT bypass signal to bypass the output routing multiplexers and feed the I/O cell directly. The enhanced ORP of the ispMACH 4000 family consists of the following elements:

- Output Routing Multiplexers
- OE Routing Multiplexers
- Output Routing Pool Bypass Multiplexers

Figure 7 shows the structure of the ORP from the I/O cell perspective. This is referred to as an ORP slice. Each ORP has as many ORP slices as there are I/O cells in the corresponding I/O block.

Figure 7. ORP Slice



Output Routing Multiplexers

The details of connections between the macrocells and the I/O cells vary across devices and within a device dependent on the maximum number of I/Os available. Tables 5-9 provide the connection details.

Table 6. ORP Combinations for I/O Blocks with 8 I/Os

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M2, M3, M4, M5, M6, M7, M8, M9
I/O 2	M4, M5, M6, M7, M8, M9, M10, M11
I/O 3	M6, M7, M8, M9, M10, M11, M12, M13
I/O 4	M8, M9, M10, M11, M12, M13, M14, M15
I/O 5	M10, M11, M12, M13, M14, M15, M0, M1
I/O 6	M12, M13, M14, M15, M0, M1, M2, M3
I/O 7	M14, M15, M0, M1, M2, M3, M4, M5

Table 7. ORP Combinations for I/O Blocks with 16 I/Os

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M1, M2, M3, M4, M5, M6, M7, M8
I/O 2	M2, M3, M4, M5, M6, M7, M8, M9
I/O 3	M3, M4, M5, M6, M7, M8, M9, M10
I/O 4	M4, M5, M6, M7, M8, M9, M10, M11
I/O 5	M5, M6, M7, M8, M9, M10, M11, M12
I/O 6	M6, M7, M8, M9, M10, M11, M12, M13
I/O 7	M7, M8, M9, M10, M11, M12, M13, M14
I/O 8	M8, M9, M10, M11, M12, M13, M14, M15
I/O 9	M9, M10, M11, M12, M13, M14, M15, M0
I/O 10	M10, M11, M12, M13, M14, M15, M0, M1
I/O 11	M11, M12, M13, M14, M15, M0, M1, M2
I/O 12	M12, M13, M14, M15, M0, M1, M2, M3
I/O 13	M13, M14, M15, M0, M1, M2, M3, M4
I/O 14	M14, M15, M0, M1, M2, M3, M4, M5
I/O 15	M15, M0, M1, M2, M3, M4, M5, M6

Table 8. ORP Combinations for I/O Blocks with 4 I/Os

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M4, M5, M6, M7, M8, M9, M10, M11
I/O 2	M8, M9, M10, M11, M12, M13, M14, M15
I/O 3	M12, M13, M14, M15, M0, M1, M2, M3

Table 9. ORP Combinations for I/O Blocks with 10 I/Os

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M2, M3, M4, M5, M6, M7, M8, M9
I/O 2	M4, M5, M6, M7, M8, M9, M10, M11
I/O 3	M6, M7, M8, M9, M10, M11, M12, M13
I/O 4	M8, M9, M10, M11, M12, M13, M14, M15
I/O 5	M10, M11, M12, M13, M14, M15, M0, M1
I/O 6	M12, M13, M14, M15, M0, M1, M2, M3
I/O 7	M14, M15, M0, M1, M2, M3, M4, M5
I/O 8	M2, M3, M4, M5, M6, M7, M8, M9
I/O 9	M10, M11, M12, M13, M14, M15, M0, M1

IEEE 1532-Compliant In-System Programming

Programming devices in-system provides a number of significant benefits including: rapid prototyping, lower inventory levels, higher quality and the ability to make in-field modifications. All ispMACH 4000 devices provide In-System Programming (ISP™) capability through the Boundary Scan Test Access Port. This capability has been implemented in a manner that ensures that the port remains compliant to the IEEE 1149.1 standard. By using IEEE 1149.1 as the communication interface through which ISP is achieved, users get the benefit of a standard, well-defined interface. All ispMACH 4000 devices are also compliant with the IEEE 1532 standard.

The ispMACH 4000 devices can be programmed across the commercial temperature and voltage range. The PC-based Lattice software facilitates in-system programming of ispMACH 4000 devices. The software takes the JEDEC file output produced by the design implementation software, along with information about the scan chain, and creates a set of vectors used to drive the scan chain. The software can use these vectors to drive a scan chain via the parallel port of a PC. Alternatively, the software can output files in formats understood by common automated test equipment. This equipment can then be used to program ispMACH 4000 devices during the testing of a circuit board.

User Electronic Signature

The User Electronic Signature (UES) allows the designer to include identification bits or serial numbers inside the device, stored in E²CMOS memory. The ispMACH 4000 device contains 32 UES bits that can be configured by the user to store unique data such as ID codes, revision numbers or inventory control codes.

Security Bit

A programmable security bit is provided on the ispMACH 4000 devices as a deterrent to unauthorized copying of the array configuration patterns. Once programmed, this bit defeats readback of the programmed pattern by a device programmer, securing proprietary designs from competitors. Programming and verification are also defeated by the security bit. The bit can only be reset by erasing the entire device.

Hot Socketing

The ispMACH 4000 devices are well-suited for applications that require hot socketing capability. Hot socketing a device requires that the device, during power-up and down, can tolerate active signals on the I/Os and inputs without being damaged. Additionally, it requires that the effects of I/O pin loading be minimal on active signals. The ispMACH 4000 devices provide this capability for input voltages in the range 0V to 3.0V.

Density Migration

The ispMACH 4000 family has been designed to ensure that different density devices in the same package have the same pin-out. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is possible to shift a lower utilization design targeted for a high density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

Supply Current, ispMACH 4000V/B/C (Cont.)

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I _{CC} ⁴	Standby Power Supply Current	V _{CC} = 3.3V	—	13	—	mA
		V _{CC} = 2.5V	—	13	—	mA
		V _{CC} = 1.8V	—	3	—	mA

1. T_A = 25°C, frequency = 1.0 MHz.
2. Device configured with 16-bit counters.
3. I_{CC} varies with specific device configuration and operating frequency.
4. T_A = 25°C

Supply Current, ispMACH 4000Z

Over Recommended Operating Conditions

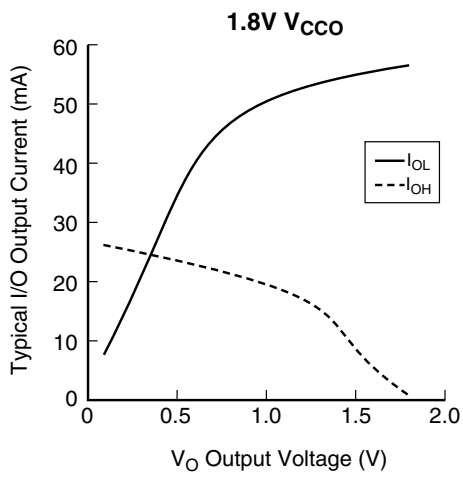
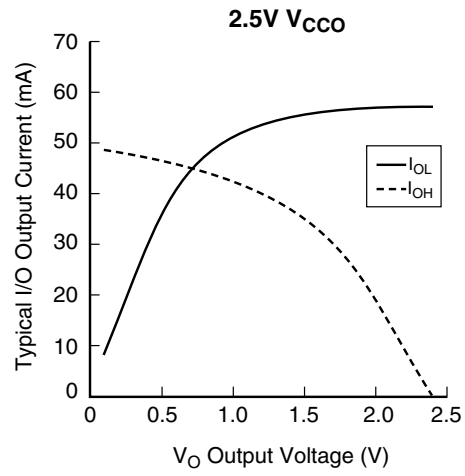
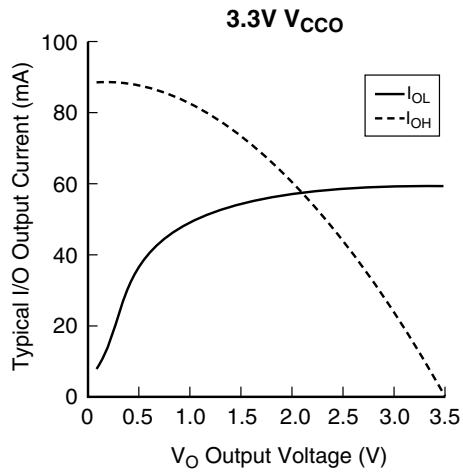
Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
ispMACH 4032ZC						
ICC ^{1,2,3,5}	Operating Power Supply Current	V _{CC} = 1.8V, T _A = 25°C	—	50	—	μA
		V _{CC} = 1.9V, T _A = 70°C	—	58	—	μA
		V _{CC} = 1.9V, T _A = 85°C	—	60	—	μA
		V _{CC} = 1.9V, T _A = 125°C	—	70	—	μA
ICC ^{4,5}	Standby Power Supply Current	V _{CC} = 1.8V, T _A = 25°C	—	10	—	μA
		V _{CC} = 1.9V, T _A = 70°C	—	13	20	μA
		V _{CC} = 1.9V, T _A = 85°C	—	15	25	μA
		V _{CC} = 1.9V, T _A = 125°C	—	22	—	μA
ispMACH 4064ZC						
ICC ^{1,2,3,5}	Operating Power Supply Current	V _{CC} = 1.8V, T _A = 25°C	—	80	—	μA
		V _{CC} = 1.9V, T _A = 70°C	—	89	—	μA
		V _{CC} = 1.9V, T _A = 85°C	—	92	—	μA
		V _{CC} = 1.9V, T _A = 125°C	—	109	—	μA
ICC ^{4,5}	Standby Power Supply Current	V _{CC} = 1.8V, T _A = 25°C	—	11	—	μA
		V _{CC} = 1.9V, T _A = 70°C	—	15	25	μA
		V _{CC} = 1.9V, T _A = 85°C	—	18	35	μA
		V _{CC} = 1.9V, T _A = 125°C	—	37	—	μA
ispMACH 4128ZC						
ICC ^{1,2,3,5}	Operating Power Supply Current	V _{CC} = 1.8V, T _A = 25°C	—	168	—	μA
		V _{CC} = 1.9V, T _A = 70°C	—	190	—	μA
		V _{CC} = 1.9V, T _A = 85°C	—	195	—	μA
		V _{CC} = 1.9V, T _A = 125°C	—	212	—	μA
ICC ^{4,5}	Standby Power Supply Current	V _{CC} = 1.8V, T _A = 25°C	—	12	—	μA
		V _{CC} = 1.9V, T _A = 70°C	—	16	35	μA
		V _{CC} = 1.9V, T _A = 85°C	—	19	50	μA
		V _{CC} = 1.9V, T _A = 125°C	—	42	—	μA

I/O DC Electrical Characteristics

Over Recommended Operating Conditions

Standard	V_{IL}		V_{IH}		V_{OL} Max (V)	V_{OH} Min (V)	I_{OL}^1 (mA)	I_{OH}^1 (mA)
	Min (V)	Max (V)	Min (V)	Max (V)				
LVTTTL	-0.3	0.80	2.0	5.5	0.40	$V_{CCO} - 0.40$	8.0	-4.0
					0.20	$V_{CCO} - 0.20$	0.1	-0.1
LVCMOS 3.3	-0.3	0.80	2.0	5.5	0.40	$V_{CCO} - 0.40$	8.0	-4.0
					0.20	$V_{CCO} - 0.20$	0.1	-0.1
LVCMOS 2.5	-0.3	0.70	1.70	3.6	0.40	$V_{CCO} - 0.40$	8.0	-4.0
					0.20	$V_{CCO} - 0.20$	0.1	-0.1
LVCMOS 1.8 (4000V/B)	-0.3	0.63	1.17	3.6	0.40	$V_{CCO} - 0.45$	2.0	-2.0
					0.20	$V_{CCO} - 0.20$	0.1	-0.1
LVCMOS 1.8 (4000C/Z)	-0.3	$0.35 * V_{CC}$	$0.65 * V_{CC}$	3.6	0.40	$V_{CCO} - 0.45$	2.0	-2.0
					0.20	$V_{CCO} - 0.20$	0.1	-0.1
PCI 3.3 (4000V/B)	-0.3	1.08	1.5	5.5	$0.1 V_{CCO}$	$0.9 V_{CCO}$	1.5	-0.5
PCI 3.3 (4000C/Z)	-0.3	$0.3 * 3.3 * (V_{CC} / 1.8)$	$0.5 * 3.3 * (V_{CC} / 1.8)$	5.5	$0.1 V_{CCO}$	$0.9 V_{CCO}$	1.5	-0.5

1. The average DC current drawn by I/Os between adjacent bank GND connections, or between the last GND in an I/O bank and the end of the I/O bank, as shown in the logic signals connection table, shall not exceed $n * 8mA$. Where n is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.



ispMACH 4000V/B/C External Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description ^{1, 2, 3}	-25		-27		-3		-35		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t _{PD}	5-PT bypass combinatorial propagation delay	—	2.5	—	2.7	—	3.0	—	3.5	ns
t _{PD_MC}	20-PT combinatorial propagation delay through macrocell	—	3.2	—	3.5	—	3.8	—	4.2	ns
t _S	GLB register setup time before clock	1.8	—	1.8	—	2.0	—	2.0	—	ns
t _{ST}	GLB register setup time before clock with T-type register	2.0	—	2.0	—	2.2	—	2.2	—	ns
t _{SIR}	GLB register setup time before clock, input register path	0.7	—	1.0	—	1.0	—	1.0	—	ns
t _{SIRZ}	GLB register setup time before clock with zero hold	1.7	—	2.0	—	2.0	—	2.0	—	ns
t _H	GLB register hold time after clock	0.0	—	0.0	—	0.0	—	0.0	—	ns
t _{HT}	GLB register hold time after clock with T-type register	0.0	—	0.0	—	0.0	—	0.0	—	ns
t _{HIR}	GLB register hold time after clock, input register path	0.9	—	1.0	—	1.0	—	1.0	—	ns
t _{HIRZ}	GLB register hold time after clock, input register path with zero hold	0.0	—	0.0	—	0.0	—	0.0	—	ns
t _{CO}	GLB register clock-to-output delay	—	2.2	—	2.7	—	2.7	—	2.7	ns
t _R	External reset pin to output delay	—	3.5	—	4.0	—	4.4	—	4.5	ns
t _{RW}	External reset pulse duration	1.5	—	1.5	—	1.5	—	1.5	-	ns
t _{P_{TOE/DIS}}	Input to output local product term output enable/disable	—	4.0	—	4.5	—	5.0	—	5.5	ns
t _{G_{P_{TOE/DIS}}}	Input to output global product term output enable/disable	—	5.0	—	6.5	—	8.0	—	8.0	ns
t _{G_{OE/DIS}}	Global OE input to output enable/disable	—	3.0	—	3.5	—	4.0	—	4.5	ns
t _{CW}	Global clock width, high or low	1.1	—	1.3	—	1.3	—	1.3	—	ns
t _{GW}	Global gate width low (for low transparent) or high (for high transparent)	1.1	—	1.3	—	1.3	—	1.3	—	ns
t _{WIR}	Input register clock width, high or low	1.1	—	1.3	—	1.3	—	1.3	—	ns
f _{MAX} ⁴	Clock frequency with internal feedback	—	400	—	333	—	322	—	322	MHz
f _{MAX} (Ext.)	Clock frequency with external feedback, [1/ (t _S + t _{CO})]	—	250	—	222	—	212	—	212	MHz

1. Timing numbers are based on default LVCMOS 1.8 I/O buffers. Use timing adjusters provided to calculate other standards.

Timing v.3.2

2. Measured using standard switching circuit, assuming GRP loading of 1 and 1 output switching.

3. Pulse widths and clock widths less than minimum will cause unknown behavior.

4. Standard 16-bit counter using GRP feedback.

ispMACH 4000Z External Switching Characteristics (Cont.)

Over Recommended Operating Conditions

Parameter	Description ^{1, 2, 3}	-45		-5		-75		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t _{PD}	5-PT bypass combinatorial propagation delay	—	4.5	—	5.0	—	7.5	ns
t _{PD_MC}	20-PT combinatorial propagation delay through macrocell	—	5.8	—	6.0	—	8.0	ns
t _S	GLB register setup time before clock	2.9	—	3.0	—	4.5	—	ns
t _{ST}	GLB register setup time before clock with T-type register	3.1	—	3.2	—	4.7	—	ns
t _{SIR}	GLB register setup time before clock, input register path	1.3	—	1.3	—	1.4	—	ns
t _{SIRZ}	GLB register setup time before clock with zero hold	2.6	—	2.6	—	2.7	—	ns
t _H	GLB register hold time after clock	0.0	—	0.0	—	0.0	—	ns
t _{HT}	GLB register hold time after clock with T-type register	0.0	—	0.0	—	0.0	—	ns
t _{HIR}	GLB register hold time after clock, input register path	1.3	—	1.3	—	1.3	—	ns
t _{HIRZ}	GLB register hold time after clock, input register path with zero hold	0.0	—	0.0	—	0.0	—	ns
t _{CO}	GLB register clock-to-output delay	—	3.8	—	4.2	—	4.5	ns
t _R	External reset pin to output delay	—	7.5	—	7.5	—	9.0	ns
t _{RW}	External reset pulse duration	2.0	—	2.0	—	4.0	—	ns
t _{P_{TOE/DIS}}	Input to output local product term output enable/disable	—	8.2	—	8.5	—	9.0	ns
t _{G_PTOE/DIS}	Input to output global product term output enable/disable	—	10.0	—	10.0	—	10.5	ns
t _{G_OE/DIS}	Global OE input to output enable/disable	—	5.5	—	6.0	—	7.0	ns
t _{CW}	Global clock width, high or low	1.8	—	2.0	—	2.8	—	ns
t _{GW}	Global gate width low (for low transparent) or high (for high transparent)	1.8	—	2.0	—	2.8	—	ns
t _{WIR}	Input register clock width, high or low	1.8	—	2.0	—	2.8	—	ns
f _{MAX} ⁴	Clock frequency with internal feedback	—	200	—	200	—	168	MHz
f _{MAX} (Ext.)	clock frequency with external feedback, [1 / (t _S + t _{CO})]	—	150	—	139	—	111	MHz

1. Timing numbers are based on default LVCMOS 1.8 I/O buffers. Use timing adjusters provided to calculate other standards.

Timing v.2.2

2. Measured using standard switching GRP loading of 1 and 1 output switching.

3. Pulse widths and clock widths less than minimum will cause unknown behavior.

4. Standard 16-bit counter using GRP feedback.

ispMACH 4000V/B/C Internal Timing Parameters

Over Recommended Operating Conditions

Parameter	Description	-5		-75		-10		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
In/Out Delays								
t _{IN}	Input Buffer Delay	—	0.95	—	1.50	—	2.00	ns
t _{GOE}	Global OE Pin Delay	—	4.04	—	6.04	—	7.04	ns
t _{GCLK_IN}	Global Clock Input Buffer Delay	—	1.83	—	2.28	—	3.28	ns
t _{BUF}	Delay through Output Buffer	—	1.00	—	1.50	—	1.50	ns
t _{EN}	Output Enable Time	—	0.96	—	0.96	—	0.96	ns
t _{DIS}	Output Disable Time	—	0.96	—	0.96	—	0.96	ns
Routing/GLB Delays								
t _{ROUTE}	Delay through GRP	—	1.51	—	2.26	—	3.26	ns
t _{MCELL}	Macrocell Delay	—	1.05	—	1.45	—	1.95	ns
t _{INREG}	Input Buffer to Macrocell Register Delay	—	0.56	—	0.96	—	1.46	ns
t _{FBK}	Internal Feedback Delay	—	0.00	—	0.00	—	0.00	ns
t _{PDb}	5-PT Bypass Propagation Delay	—	1.54	—	2.24	—	3.24	ns
t _{PDi}	Macrocell Propagation Delay	—	0.94	—	1.24	—	1.74	ns
Register/Latch Delays								
t _S	D-Register Setup Time (Global Clock)	1.32	—	1.57	—	1.57	—	ns
t _{S_PT}	D-Register Setup Time (Product Term Clock)	1.32	—	1.32	—	1.32	—	ns
t _{ST}	T-Register Setup Time (Global Clock)	1.52	—	1.77	—	1.77	—	ns
t _{ST_PT}	T-Register Setup Time (Product Term Clock)	1.32	—	1.32	—	1.32	—	ns
t _H	D-Register Hold Time	1.68	—	2.93	—	3.93	—	ns
t _{HT}	T-Register Hold Time	1.68	—	2.93	—	3.93	—	ns
t _{SIR}	D-Input Register Setup Time (Global Clock)	1.52	—	1.57	—	1.57	—	ns
t _{SIR_PT}	D-Input Register Setup Time (Product Term Clock)	1.45	—	1.45	—	1.45	—	ns
t _{HIR}	D-Input Register Hold Time (Global Clock)	0.68	—	1.18	—	1.18	—	ns
t _{HIR_PT}	D-Input Register Hold Time (Product Term Clock)	0.68	—	1.18	—	1.18	—	ns
t _{COi}	Register Clock to Output/Feedback MUX Time	—	0.52	—	0.67	—	1.17	ns
t _{CES}	Clock Enable Setup Time	2.25	—	2.25	—	2.25	—	ns
t _{CEH}	Clock Enable Hold Time	1.88	—	1.88	—	1.88	—	ns
t _{SL}	Latch Setup Time (Global Clock)	1.32	—	1.57	—	1.57	—	ns
t _{SL_PT}	Latch Setup Time (Product Term Clock)	1.32	—	1.32	—	1.32	—	ns
t _{HL}	Latch Hold Time	1.17	—	1.17	—	1.17	—	ns
t _{GOi}	Latch Gate to Output/Feedback MUX Time	—	0.33	—	0.33	—	0.33	ns
t _{PDLi}	Propagation Delay through Transparent Latch to Output/Feedback MUX	—	0.25	—	0.25	—	0.25	ns
t _{SRI}	Asynchronous Reset or Set to Output/Feedback MUX Delay	0.28	—	0.28	—	0.28	—	ns
t _{SRR}	Asynchronous Reset or Set Recovery Time	1.67	—	1.67	—	1.67	—	ns
Control Delays								
t _{BCLK}	GLB PT Clock Delay	—	1.12	—	1.12	—	0.62	ns
t _{PTCLK}	Macrocell PT Clock Delay	—	0.87	—	0.87	—	0.87	ns
t _{BSR}	GLB PT Set/Reset Delay	—	1.83	—	1.83	—	1.83	ns
t _{PTSR}	Macrocell PT Set/Reset Delay	—	2.51	—	3.41	—	3.41	ns

ispMACH 4032Z and 4064Z Logic Signal Connections: 56-Ball csBGA (Cont.)

Ball Number	Bank Number	ispMACH 4032Z		ispMACH 4064Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
K5	0	A15	A ¹⁵	B0	B ⁰
H6	0	CLK1/I	-	CLK1/I	-
K6	1	CLK2/I	-	CLK2/I	-
H7	1	B0	B ⁰	C0	C ⁰
K7	1	B1	B ¹	C1	C ¹
K8	1	B2	B ²	C2	C ²
K9	1	B3	B ³	C4	C ³
K10	1	B4	B ⁴	C6	C ⁴
J10	-	TMS	-	TMS	-
H8	1	B5	B ⁵	C8	C ⁵
H10	1	B6	B ⁶	C10	C ⁶
G10	1	B7	B ⁷	C11	C ⁷
G8	1	GND (Bank 1)	-	GND (Bank 1)	-
F8	1	NC ¹	-	I ¹	-
F10	1	NC ¹	-	I ¹	-
E8	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
E10	1	B8	B ⁸	D15	D ⁷
D8	1	B9	B ⁹	D12	D ⁶
D10	1	B10	B ¹⁰	D10	D ⁵
C10	1	B11	B ¹¹	D8	D ⁴
B10	1	NC ¹	-	I ¹	-
A10	-	TDO	-	TDO	-
A9	-	VCC	-	VCC	-
C8	-	GND	-	GND	-
A8	1	NC ¹	-	I ¹	-
A7	1	B12	B ¹²	D6	D ³
C7	1	B13	B ¹³	D4	D ²
C6	1	B14	B ¹⁴	D2	D ¹
A6	1	B15/GOE1	B ¹⁵	D0/GOE1	D ⁰
C5	1	CLK3/I	-	CLK3/I	-
A5	0	CLK0/I	-	CLK0/I	-
C4	0	A0/GOE0	A ⁰	A0/GOE0	A ⁰
A4	0	A1	A ¹	A1	A ¹
A3	0	A2	A ²	A2	A ²
A2	0	A3	A ³	A4	A ³
A1	0	A4	A ⁴	A6	A ⁴

1. For device migration considerations, these NC pins are input signal pins in ispMACH 4064Z devices.

ispMACH 4128V/B/C Logic Signal Connections: 128-Pin TQFP (Cont.)

Pin Number	Bank Number	ispMACH 4128V/B/C	
		GLB/MC/Pad	ORP
105	1	VCCO (Bank 1)	-
106	1	H6	H^5
107	1	H5	H^4
108	1	H4	H^3
109	1	H2	H^2
110	1	H1	H^1
111	1	H0/GOE1	H^0
112	1	CLK3/I	-
113	0	GND (Bank 0)	-
114	0	CLK0/I	-
115	0	VCC	-
116	0	A0/GOE0	A^0
117	0	A1	A^1
118	0	A2	A^2
119	0	A4	A^3
120	0	A5	A^4
121	0	A6	A^5
122	0	VCCO (Bank 0)	-
123	0	GND (Bank 0)	-
124	0	A8	A^6
125	0	A9	A^7
126	0	A10	A^8
127	0	A12	A^9
128	0	A14	A^11

ispMACH 4064Z, 4128Z and 4256Z Logic Signal Connections: 132-Ball csBGA

Ball Number	Bank Number	ispMACH 4064Z		ispMACH 4128Z		ispMACH 4256Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
B1	-	GND	-	GND	-	GND	-
B2	-	TDI	-	TDI	-	TDI	-
C1	0	NC	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
C3	0	NC	-	B0	B^0	C12	C^6
C2	0	A8	A^8	B1	B^1	C10	C^5
D1	0	A9	A^9	B2	B^2	C8	C^4
D3	0	A10	A^10	B4	B^3	C6	C^3
D2	0	A11	A^11	B5	B^4	C4	C^2
E1	0	NC	-	B6	B^5	C2	C^1
E2	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-

**ispMACH 4256V/B/C/Z, 4384V/B/C, 4512V/B/C, Logic Signal Connections:
176-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4256V/B/C/Z		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
60	0	H8	H ⁴	L8	L ⁴	P8	P ⁴
61	0	H6	H ³	L6	L ³	P6	P ³
62	0	H4	H ²	L4	L ²	P4	P ²
63	0	H2	H ¹	L2	L ¹	P2	P ¹
64	0	H0	H ⁰	L0	L ⁰	P0	P ⁰
65	-	GND	-	GND	-	GND	-
66	0	CLK1/I	-	CLK1/I	-	CLK1/I	-
67	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
68	1	CLK2/I	-	CLK2/I	-	CLK2/I	-
69	-	VCC	-	VCC	-	VCC	-
70	1	I0	I ⁰	M0	M ⁰	AX0	AX ⁰
71	1	I2	I ¹	M2	M ¹	AX2	AX ¹
72	1	I4	I ²	M4	M ²	AX4	AX ²
73	1	I6	I ³	M6	M ³	AX6	AX ³
74	1	I8	I ⁴	M8	M ⁴	AX8	AX ⁴
75	1	I10	I ⁵	M10	M ⁵	AX10	AX ⁵
76	1	I12	I ⁶	M12	M ⁶	AX12	AX ⁶
77	1	I14	I ⁷	M14	M ⁷	AX14	AX ⁷
78	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
79	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
80	1	J0	J ⁰	N0	N ⁰	BX0	BX ⁰
81	1	J2	J ¹	N2	N ¹	BX2	BX ¹
82	1	J4	J ²	N4	N ²	BX4	BX ²
83	1	J6	J ³	N6	N ³	BX6	BX ³
84	1	J8	J ⁴	N8	N ⁴	BX8	BX ⁴
85	1	J10	J ⁵	N10	N ⁵	BX10	BX ⁵
86	1	J12	J ⁶	N12	N ⁶	BX12	BX ⁶
87	1	J14	J ⁷	N14	N ⁷	BX14	BX ⁷
88	-	VCC	-	VCC	-	VCC	-
89	-	NC	-	NC	-	NC	-
90	-	GND	-	GND	-	GND	-
91	-	TMS	-	TMS	-	TMS	-
92	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
93	1	K14	K ⁷	O14	O ⁷	CX14	CX ⁷
94	1	K12	K ⁶	O12	O ⁶	CX12	CX ⁶
95	1	K10	K ⁵	O10	O ⁵	CX10	CX ⁵
96	1	K8	K ⁴	O8	O ⁴	CX8	CX ⁴
97	1	K6	K ³	O6	O ³	CX6	CX ³
98	1	K4	K ²	O4	O ²	CX4	CX ²
99	1	K2	K ¹	O2	O ¹	CX2	CX ¹
100	1	K0	K ⁰	O0	O ⁰	CX0	CX ⁰

**ispMACH 4256V/B/C, 4384V/B/C, 4512V/B/C Logic Signal Connections:
256-Ball ftBGA/fpBGA (Cont.)**

Ball Number	I/O Bank	ispMACH 4256V/B/C 128-I/O		ispMACH 4256V/B/C 160-I/O		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
E7	0	NC	-	B1	B^1	F8	F^4	D12	D^3
A3	0	B0	B^0	B2	B^2	B0	B^0	B0	B^0
F7	0	B2	B^1	B4	B^3	B2	B^1	B2	B^1
B4	0	B4	B^2	B6	B^4	B4	B^2	B4	B^2
C5	0	B6	B^3	B8	B^5	B6	B^3	B6	B^3
A2	0	B8	B^4	B9	B^6	B8	B^4	B8	B^4
E6	0	B10	B^5	B10	B^7	B10	B^5	B10	B^5
B3	0	B12	B^6	B12	B^8	B12	B^6	B12	B^6
C4	0	B14	B^7	B14	B^9	B14	B^7	B14	B^7
D4	0	NC	-	NC	-	D10	D^5	F0	F^0
E5	0	NC	-	NC	-	D8	D^4	F2	F^1
-	-	VCC	-	VCC	-	VCC	-	VCC	-
-	-	-	-	-	-	GND	-	GND	-
-	0	-	-	-	-	GND (Bank 0)	-	GND (Bank 0)	-

Note: VCC, VCCO and GND are tied together to their respective common signal on the package substrate. See Power Supply and NC Connections table for VCC/ VCCO/GND pin definitions.

ispMACH 4000ZC (1.8V, Zero Power) Industrial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4064ZC	LC4064ZC-5M132I	64	1.8	5	csBGA	132	64	I
	LC4064ZC-75M132I	64	1.8	7.5	csBGA	132	64	I
	LC4064ZC-5T100I	64	1.8	5	TQFP	100	64	I
	LC4064ZC-75T100I	64	1.8	7.5	TQFP	100	64	I
	LC4064ZC-5M56I	64	1.8	5	csBGA	56	34	I
	LC4064ZC-75M56I	64	1.8	7.5	csBGA	56	34	I
	LC4064ZC-5T48I	64	1.8	5	TQFP	48	32	I
	LC4064ZC-75T48I	64	1.8	7.5	TQFP	48	32	I
LC4128ZC	LC4128ZC-75M132I	128	1.8	7.5	csBGA	132	96	I
	LC4128ZC-75T100I	128	1.8	7.5	TQFP	100	64	I
LC4256ZC	LC4256ZC-75T176I	256	1.8	7.5	TQFP	176	128	I
	LC4256ZC-75M132I	256	1.8	7.5	csBGA	132	96	I
	LC4256ZC-75T100I	256	1.8	7.5	TQFP	100	64	I

ispMACH 4000ZC (1.8V, Zero Power) Extended Temperature Devices

Family	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032ZC	LC4032ZC-75T48E	32	1.8	7.5	TQFP	48	32	E
LC4064ZC	LC4064ZC-75T100E	64	1.8	7.5	TQFP	100	64	E
	LC4064ZC-75T48E	64	1.8	7.5	TQFP	48	32	E
LC4128ZC	LC4128ZC-75T100E	128	1.8	7.5	TQFP	100	64	E
LC4256ZC	LC4256ZC-75T176E	256	1.8	7.5	TQFP	176	128	E
	LC4256ZC-75T100E	256	1.8	7.5	TQFP	100	64	E

ispMACH 4000C (1.8V) Commercial Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032C	LC4032C-25T48C	32	1.8	2.5	TQFP	48	32	C
	LC4032C-5T48C	32	1.8	5	TQFP	48	32	C
	LC4032C-75T48C	32	1.8	7.5	TQFP	48	32	C
	LC4032C-25T44C	32	1.8	2.5	TQFP	44	30	C
	LC4032C-5T44C	32	1.8	5	TQFP	44	30	C
	LC4032C-75T44C	32	1.8	7.5	TQFP	44	30	C
LC4064C	LC4064C-25T100C	64	1.8	2.5	TQFP	100	64	C
	LC4064C-5T100C	64	1.8	5	TQFP	100	64	C
	LC4064C-75T100C	64	1.8	7.5	TQFP	100	64	C
	LC4064C-25T48C	64	1.8	2.5	TQFP	48	32	C
	LC4064C-5T48C	64	1.8	5	TQFP	48	32	C
	LC4064C-75T48C	64	1.8	7.5	TQFP	48	32	C
	LC4064C-25T44C	64	1.8	2.5	TQFP	44	30	C
	LC4064C-5T44C	64	1.8	5	TQFP	44	30	C
LC4064C-75T44C	64	1.8	7.5	TQFP	44	30	C	

ispMACH 4000V (3.3V) Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4128V	LC4128V-27T144C	128	3.3	2.7	TQFP	144	96	C
	LC4128V-5T144C	128	3.3	5	TQFP	144	96	C
	LC4128V-75T144C	128	3.3	7.5	TQFP	144	96	C
	LC4128V-27T128C	128	3.3	2.7	TQFP	128	92	C
	LC4128V-5T128C	128	3.3	5	TQFP	128	92	C
	LC4128V-75T128C	128	3.3	7.5	TQFP	128	92	C
	LC4128V-27T100C	128	3.3	2.7	TQFP	100	64	C
	LC4128V-5T100C	128	3.3	5	TQFP	100	64	C
	LC4128V-75T100C	128	3.3	7.5	TQFP	100	64	C
LC4256V	LC4256V-3FT256AC	256	3.3	3	ftBGA	256	128	C
	LC4256V-5FT256AC	256	3.3	5	ftBGA	256	128	C
	LC4256V-75FT256AC	256	3.3	7.5	ftBGA	256	128	C
	LC4256V-3FT256BC	256	3.3	3	ftBGA	256	160	C
	LC4256V-5FT256BC	256	3.3	5	ftBGA	256	160	C
	LC4256V-75FT256BC	256	3.3	7.5	ftBGA	256	160	C
	LC4256V-3F256AC ¹	256	3.3	3	fpBGA	256	128	C
	LC4256V-5F256AC ¹	256	3.3	5	fpBGA	256	128	C
	LC4256V-75F256AC ¹	256	3.3	7.5	fpBGA	256	128	C
	LC4256V-3F256BC ¹	256	3.3	3	fpBGA	256	160	C
	LC4256V-5F256BC ¹	256	3.3	5	fpBGA	256	160	C
	LC4256V-75F256BC ¹	256	3.3	7.5	fpBGA	256	160	C
	LC4256V-3T176C	256	3.3	3	TQFP	176	128	C
	LC4256V-5T176C	256	3.3	5	TQFP	176	128	C
	LC4256V-75T176C	256	3.3	7.5	TQFP	176	128	C
	LC4256V-3T144C	256	3.3	3	TQFP	144	96	C
	LC4256V-5T144C	256	3.3	5	TQFP	144	96	C
	LC4256V-75T144C	256	3.3	7.5	TQFP	144	96	C
	LC4256V-3T100C	256	3.3	3	TQFP	100	64	C
	LC4256V-5T100C	256	3.3	5	TQFP	100	64	C
LC4256V-75T100C	256	3.3	7.5	TQFP	100	64	C	
LC4384V	LC4384V-35FT256C	384	3.3	3.5	ftBGA	256	192	C
	LC4384V-5FT256C	384	3.3	5	ftBGA	256	192	C
	LC4384V-75FT256C	384	3.3	7.5	ftBGA	256	192	C
	LC4384V-35F256C ¹	384	3.3	3.5	fpBGA	256	192	C
	LC4384V-5F256C ¹	384	3.3	5	fpBGA	256	192	C
	LC4384V-75F256C ¹	384	3.3	7.5	fpBGA	256	192	C
	LC4384V-35T176C	384	3.3	3.5	TQFP	176	128	C
	LC4384V-5T176C	384	3.3	5	TQFP	176	128	C
	LC4384V-75T176C	384	3.3	7.5	TQFP	176	128	C

ispMACH 4000V (3.3V) Industrial Devices (Cont.)

Family	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4256V	LC4256V-5FT256AI	256	3.3	5	ftBGA	256	128	I
	LC4256V-75FT256AI	256	3.3	7.5	ftBGA	256	128	I
	LC4256V-10FT256AI	256	3.3	10	ftBGA	256	128	I
	LC4256V-5FT256BI	256	3.3	5	ftBGA	256	160	I
	LC4256V-75FT256BI	256	3.3	7.5	ftBGA	256	160	I
	LC4256V-10FT256BI	256	3.3	10	ftBGA	256	160	I
	LC4256V-5F256AI ¹	256	3.3	5	fpBGA	256	128	I
	LC4256V-75F256AI ¹	256	3.3	7.5	fpBGA	256	128	I
	LC4256V-10F256AI ¹	256	3.3	10	fpBGA	256	128	I
	LC4256V-5F256BI ¹	256	3.3	5	fpBGA	256	160	I
	LC4256V-75F256BI ¹	256	3.3	7.5	fpBGA	256	160	I
	LC4256V-10F256BI ¹	256	3.3	10	fpBGA	256	160	I
	LC4256V-5T176I	256	3.3	5	TQFP	176	128	I
	LC4256V-75T176I	256	3.3	7.5	TQFP	176	128	I
	LC4256V-10T176I	256	3.3	10	TQFP	176	128	I
	LC4256V-5T144I	256	3.3	5	TQFP	144	96	I
	LC4256V-75T144I	256	3.3	7.5	TQFP	144	96	I
	LC4256V-10T144I	256	3.3	10	TQFP	144	96	I
	LC4256V-5T100I	256	3.3	5	TQFP	100	64	I
	LC4256V-75T100I	256	3.3	7.5	TQFP	100	64	I
LC4256V-10T100I	256	3.3	10	TQFP	100	64	I	
LC4384V	LC4384V-5FT256I	384	3.3	5	ftBGA	256	192	I
	LC4384V-75FT256I	384	3.3	7.5	ftBGA	256	192	I
	LC4384V-10FT256I	384	3.3	10	ftBGA	256	192	I
	LC4384V-5F256I ¹	384	3.3	5	fpBGA	256	192	I
	LC4384V-75F256I ¹	384	3.3	7.5	fpBGA	256	192	I
	LC4384V-10F256I ¹	384	3.3	10	fpBGA	256	192	I
	LC4384V-5T176I	384	3.3	5	TQFP	176	128	I
	LC4384V-75T176I	384	3.3	7.5	TQFP	176	128	I
	LC4384V-10T176I	384	3.3	10	TQFP	176	128	I
LC4512V	LC4512V-5FT256I	512	3.3	5	ftBGA	256	208	I
	LC4512V-75FT256I	512	3.3	7.5	ftBGA	256	208	I
	LC4512V-10FT256I	512	3.3	10	ftBGA	256	208	I
	LC4512V-5F256I ¹	512	3.3	5	fpBGA	256	208	I
	LC4512V-75F256I ¹	512	3.3	7.5	fpBGA	256	208	I
	LC4512V-10F256I ¹	512	3.3	10	fpBGA	256	208	I
	LC4512V-5T176I	512	3.3	5	TQFP	176	128	I
	LC4512V-75T176I	512	3.3	7.5	TQFP	176	128	I
	LC4512V-10T176I	512	3.3	10	TQFP	176	128	I

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

ispMACH 4000V (3.3V) Extended Temperature Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032V	LC4032V-75T48E	32	3.3	7.5	TQFP	48	32	E
	LC4032V-75T44E	32	3.3	7.5	TQFP	44	30	E
LC4064V	LC4064V-75T100E	64	3.3	7.5	TQFP	100	64	E
	LC4064V-75T48E	64	3.3	7.5	TQFP	48	32	E
	LC4064V-75T44E	64	3.3	7.5	TQFP	44	30	E
LC4128V	LC4128V-75T144E	128	3.3	7.5	TQFP	144	96	E
	LC4128V-75T128E	128	3.3	7.5	TQFP	128	92	E
	LC4128V-75T100E	128	3.3	7.5	TQFP	100	64	E
LC4256V	LC4256V-75T176E	256	3.3	7.5	TQFP	176	128	E
	LC4256V-75T144E	256	3.3	7.5	TQFP	144	96	E
	LC4256V-75T100E	256	3.3	7.5	TQFP	100	64	E

Lead-Free Packaging**ispMACH 4000Z (Zero Power, 1.8V) Lead-Free Commercial Devices**

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032ZC	LC4032ZC-35MN56C	32	1.8	3.5	Lead-free csBGA	56	32	C
	LC4032ZC-5MN56C	32	1.8	5	Lead-free csBGA	56	32	C
	LC4032ZC-75MN56C	32	1.8	7.5	Lead-free csBGA	56	32	C
	LC4032ZC-35TN48C	32	1.8	3.5	Lead-free TQFP	48	32	C
	LC4032ZC-5TN48C	32	1.8	5	Lead-free TQFP	48	32	C
	LC4032ZC-75TN48C	32	1.8	7.5	Lead-free TQFP	48	32	C
LC4064ZC	LC4064ZC-37MN132C	64	1.8	3.7	Lead-free csBGA	132	64	C
	LC4064ZC-5MN132C	64	1.8	5	Lead-free csBGA	132	64	C
	LC4064ZC-75MN132C	64	1.8	7.5	Lead-free csBGA	132	64	C
	LC4064ZC-37TN100C	64	1.8	3.7	Lead-free TQFP	100	64	C
	LC4064ZC-5TN100C	64	1.8	5	Lead-free TQFP	100	64	C
	LC4064ZC-75TN100C	64	1.8	7.5	Lead-free TQFP	100	64	C
	LC4064ZC-37MN56C	64	1.8	3.7	Lead-free csBGA	56	32	C
	LC4064ZC-5MN56C	64	1.8	5	Lead-free csBGA	56	32	C
	LC4064ZC-75MN56C	64	1.8	7.5	Lead-free csBGA	56	32	C
	LC4064ZC-37TN48C	64	1.8	3.7	Lead-free TQFP	48	32	C
	LC4064ZC-5TN48C	64	1.8	5	Lead-free TQFP	48	32	C
LC4064ZC-75TN48C	64	1.8	7.5	Lead-free TQFP	48	32	C	
LC4128ZC	LC4128ZC-42MN132C	128	1.8	4.2	Lead-free csBGA	132	96	C
	LC4128ZC-75MN132C	128	1.8	7.5	Lead-free csBGA	132	96	C
	LC4128ZC-42TN100C	128	1.8	4.2	Lead-free TQFP	100	64	C
	LC4128ZC-75TN100C	128	1.8	7.5	Lead-free TQFP	100	64	C
LC4256ZC	LC4256ZC-45TN176C	256	1.8	4.5	Lead-free TQFP	176	128	C
	LC4256ZC-75TN176C	256	1.8	7.5	Lead-free TQFP	176	128	C
	LC4256ZC-45MN132C	256	1.8	4.5	Lead-free csBGA	132	96	C
	LC4256ZC-75MN132C	256	1.8	7.5	Lead-free csBGA	132	96	C
	LC4256ZC-45TN100C	256	1.8	4.5	Lead-free TQFP	100	64	C
	LC4256ZC-75TN100C	256	1.8	7.5	Lead-free TQFP	100	64	C

ispMACH 4000Z (Zero Power, 1.8V) Lead-Free Industrial Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032ZC	LC4032ZC-5MN56I	32	1.8	5	Lead-free csBGA	56	32	I
	LC4032ZC-75MN56I	32	1.8	7.5	Lead-free csBGA	56	32	I
	LC4032ZC-5TN48I	32	1.8	5	Lead-free TQFP	48	32	I
	LC4032ZC-75TN48I	32	1.8	7.5	Lead-free TQFP	48	32	I

ispMACH 4000V (3.3V) Lead-Free Industrial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4256V	LC4256V-5FTN256AI	256	3.3	5	Lead-free ftBGA	256	128	I
	LC4256V-75FTN256AI	256	3.3	7.5	Lead-free ftBGA	256	128	I
	LC4256V-10FTN256AI	256	3.3	10	Lead-free ftBGA	256	128	I
	LC4256V-5FTN256BI	256	3.3	5	Lead-free ftBGA	256	160	I
	LC4256V-75FTN256BI	256	3.3	7.5	Lead-free ftBGA	256	160	I
	LC4256V-10FTN256BI	256	3.3	10	Lead-free ftBGA	256	160	I
	LC4256V-5FN256AI ¹	256	3.3	5	Lead-free fpBGA	256	128	I
	LC4256V-75FN256AI ¹	256	3.3	7.5	Lead-free fpBGA	256	128	I
	LC4256V-10FN256AI ¹	256	3.3	10	Lead-free fpBGA	256	128	I
	LC4256V-5FN256BI ¹	256	3.3	5	Lead-free fpBGA	256	160	I
	LC4256V-75FN256BI ¹	256	3.3	7.5	Lead-free fpBGA	256	160	I
	LC4256V-10FN256BI ¹	256	3.3	10	Lead-free fpBGA	256	160	I
	LC4256V-5TN176I	256	3.3	5	Lead-free TQFP	176	128	I
	LC4256V-75TN176I	256	3.3	7.5	Lead-free TQFP	176	128	I
	LC4256V-10TN176I	256	3.3	10	Lead-free TQFP	176	128	I
	LC4256V-5TN144I	256	3.3	5	Lead-free TQFP	144	96	I
	LC4256V-75TN144I	256	3.3	7.5	Lead-free TQFP	144	96	I
	LC4256V-10TN144I	256	3.3	10	Lead-free TQFP	144	96	I
	LC4256V-5TN100I	256	3.3	5	Lead-free TQFP	100	64	I
	LC4256V-75TN100I	256	3.3	7.5	Lead-free TQFP	100	64	I
LC4256V-10TN100I	256	3.3	10	Lead-free TQFP	100	64	I	
LC4384V	LC4384V-5FTN256I	384	3.3	5	Lead-free ftBGA	256	192	I
	LC4384V-75FTN256I	384	3.3	7.5	Lead-free ftBGA	256	192	I
	LC4384V-10FTN256I	384	3.3	10	Lead-free ftBGA	256	192	I
	LC4384V-5FN256I ¹	384	3.3	5	Lead-free fpBGA	256	192	I
	LC4384V-75FN256I ¹	384	3.3	7.5	Lead-free fpBGA	256	192	I
	LC4384V-10FN256I ¹	384	3.3	10	Lead-free fpBGA	256	192	I
	LC4384V-5TN176I	384	3.3	5	Lead-free TQFP	176	128	I
	LC4384V-75TN176I	384	3.3	7.5	Lead-free TQFP	176	128	I
LC4384V-10TN176I	384	3.3	10	Lead-free TQFP	176	128	I	
LC4512V	LC4512V-5FTN256I	512	3.3	5	Lead-free ftBGA	256	208	I
	LC4512V-75FTN256I	512	3.3	7.5	Lead-free ftBGA	256	208	I
	LC4512V-10FTN256I	512	3.3	10	Lead-free ftBGA	256	208	I
	LC4512V-5FN256I ¹	512	3.3	5	Lead-free fpBGA	256	208	I
	LC4512V-75FN256I ¹	512	3.3	7.5	Lead-free fpBGA	256	208	I
	LC4512V-10FN256I ¹	512	3.3	10	Lead-free fpBGA	256	208	I
	LC4512V-5TN176I	512	3.3	5	Lead-free TQFP	176	128	I
	LC4512V-75TN176I	512	3.3	7.5	Lead-free TQFP	176	128	I
	LC4512V-10TN176I	512	3.3	10	Lead-free TQFP	176	128	I

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.